

LNJ923W8FRAW

Ultra High Bright Surface Mounting Chip LED

Blue Side View Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

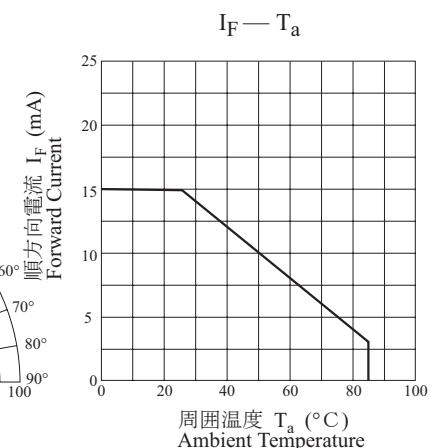
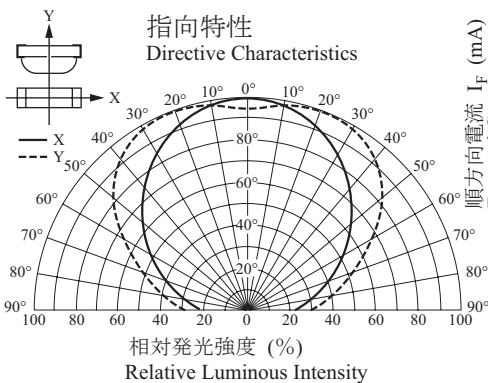
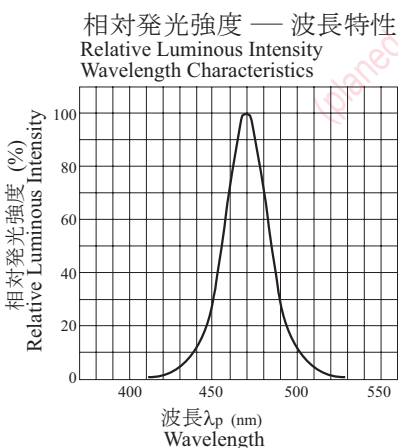
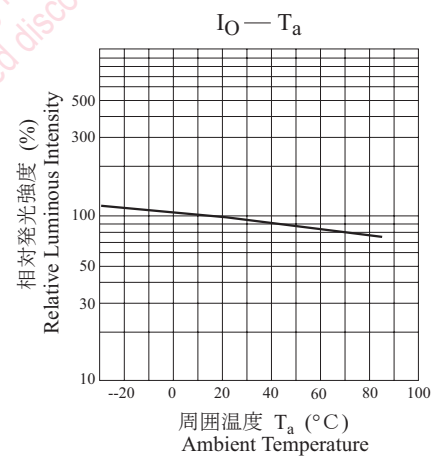
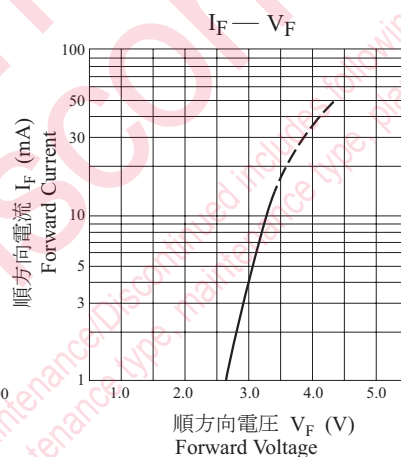
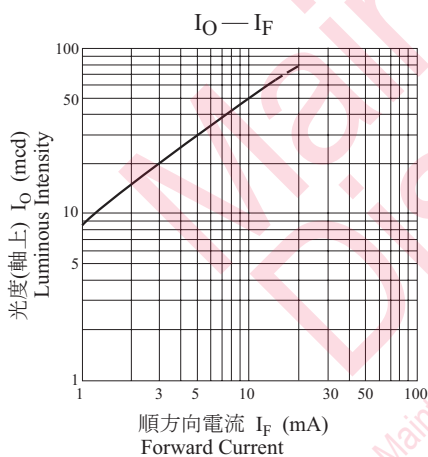
Parameter	Symbol	Rating	Unit
Power dissipation	P_D	65	mW/chip
Forward current	I_F	15	mA/chip
Pulse forward current	I_{FP}	50	mA/chip
Reverse direct current	I_{RDC}	100	mA/chip
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

■ Lighting Color

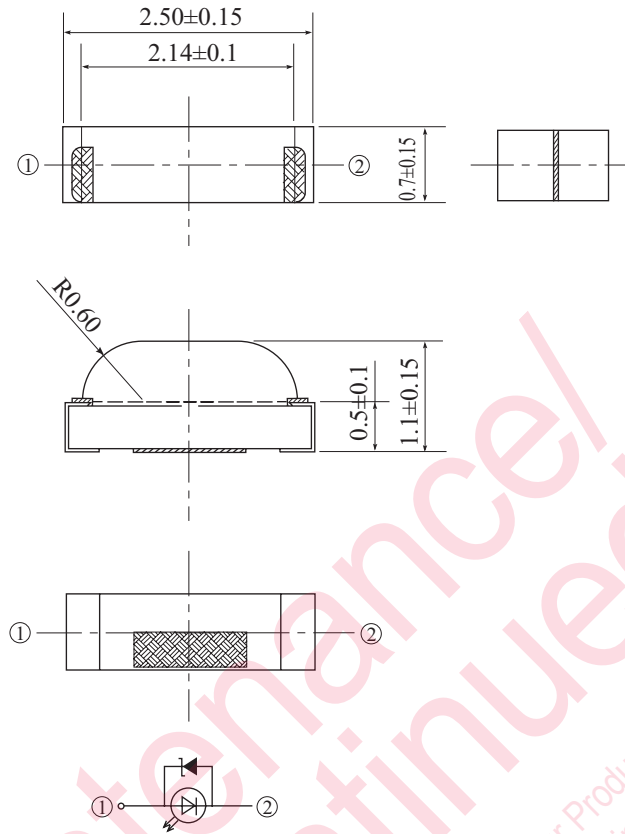
- Blue

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O	$V_F = 2.91\text{ V}$	3	20		mcd
Forward voltage	V_F	$I_F = 5\text{ mA DC}$		3.1	3.7	V
Peak emission wavelength	λ_p	$I_F = 5\text{ mA DC}$		470		nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA DC}$		30		nm



■ Package (Unit: mm)



- Pin name
- 1: Anode
- 2: Cathode

Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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